

Microarchitecture in the System-level Integration Era

Featuring Jenny Koerv as Chuck Moore



What is the System-level Integration Era?

- Single-chip CPU Era: 1986 – 2004
 - Extreme focus on single-threaded performance optimizations
 - Multi-issue, out-of-order execution core plus moderate cache hierarchy
- Chip Multiprocessor (CMP) Era: 2004 – 2010
 - Early: Hasty integration of multiple cores into same chip/package
 - Mid-life: Address some of the HW scalability and interference issues
 - Current: Homogeneous CPUs plus moderate system-level functionality
- System-level Integration Era: ~2010 onward
 - Integration of substantial system-level functionality
 - Heterogeneous processors and accelerators
 - Introspective control systems for managing on-chip resources & events



Enablers of the System-level Integration Era

- Moore's Law is projected to continue well beyond 22nm
 - Traditional components get really small in 22nm
 - Opteron-class core: $\sim 5 \text{ mm}^2$; 1MB fast cache memory: $\sim 4.5 \text{ mm}^2$
 - 3D chip stacking on the near horizon
 - Initially, this will mostly involve stacking various types of RAM
 - Over time, multiple chips with logical functionality
- Large customer value potential in Platform-level optimizations
 - Cost and power reductions from integration (vs. discrete chips)
 - Performance/watt/\$\$ is the new value proposition
 - Balance on-chip processing with available system-level BW
 - Balance on-chip processing with ***actual usage scenarios***



Challenges in the System-level Integration Era

- Complexity Management
 - Principles for managing exponential growth
 - Development expense and TTM
- Exploitation of available parallelism
 - Single thread performance outlook
 - Parallel threads, Throughput and Distributed computing
 - Optimized SW for System-level Solutions
- Memory system balance
- The Power Wall keeps getting *worse*

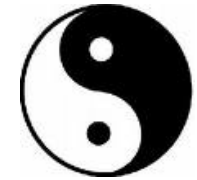


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Principles for Managing Exponential Growth



- Scarcity and Abundance: *the yin and yang of technology*
 - Leverage abundance to solve problems w/ scarcity
 - **Abundant**: *transistors, raw FLOPs, bandwidth, cores?*
 - **Scarce**: *power, latency, HW and SW productivity, TTM*
- Take advantage of Abstractions
 - Powerful and proven principle for scientific advancement
 - Already broadly used in the computer field
 - Hierarchical CAD; Embedded Design and Re-use; SW encapsulation



Development Expense and Time-to-Market

- Leading edge chip design today is **very** expensive
 - Multi-year design teams of 300-500 people, and growing fast
 - Platform Qualification (HW *and* SW): Hundreds of engineers
- Complexity & Scope challenge Time-to-Market (TTM)
 - Integration adds value, but it also adds complexity
 - Design verification methods are stretched to their limits
 - Microcode-based workarounds to bugs becoming increasingly inadequate at the system level
- Average Sales Price (ASP) in many markets continues to drop
 - Very unforgiving time-to-market expectations
 - Good for the consumer, but bad for the chip developers



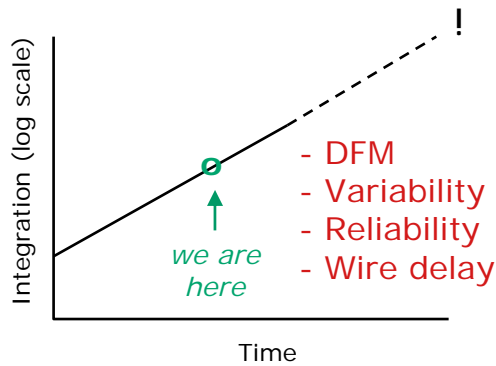
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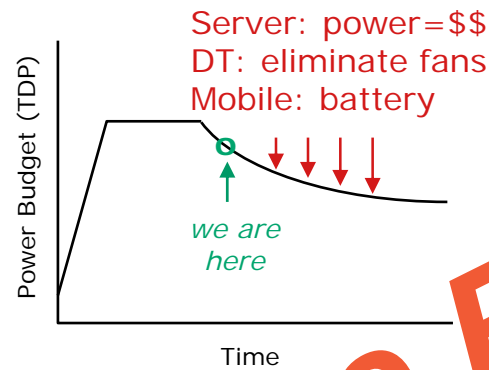


Single-thread Performance

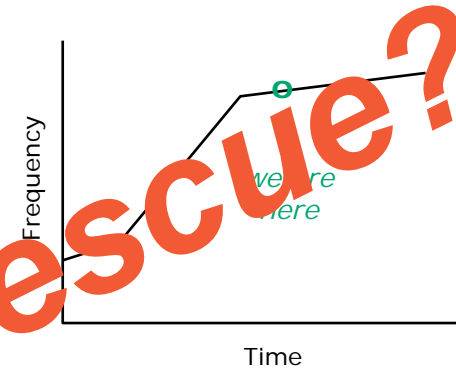
Moore's Law ☺



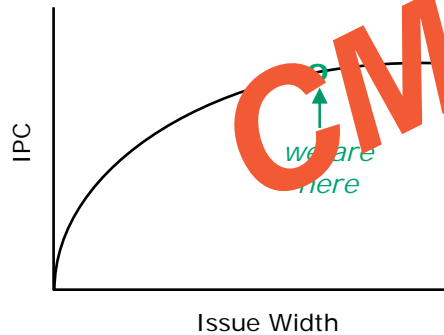
The Power Wall ☹



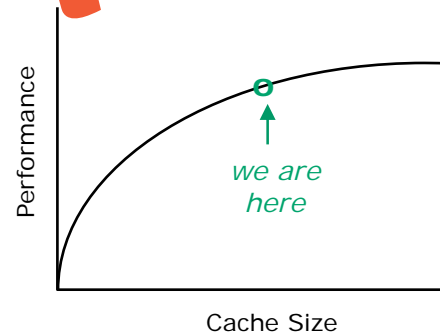
The Frequency Wall ☹



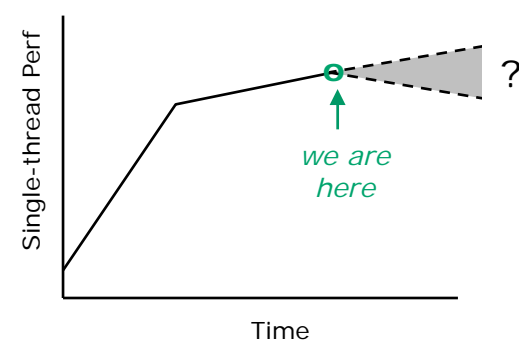
The IPC Complexity Wall ☹



Locality ☹



Single thread Perf (!)



Cooperating Subsystems must ...

- ***Communicate*** with one another & higher-level frameworks
 - Fork/Join semantics; Producer/Consumer protocols
 - OS scheduler, resource managers and exception handlers
- ***Synchronize*** the use of shared resources
 - Implicit sync through storage ordering constraints
 - Explicit sync through semaphores and locks
- Enable ***Data Movement*** for optimized performance
 - Coherent caches do a pretty good job with system memory
 - Still, for devices we often see “page pinning” & explicit moves

The resulting overhead adds to the serial component
of parallel programs

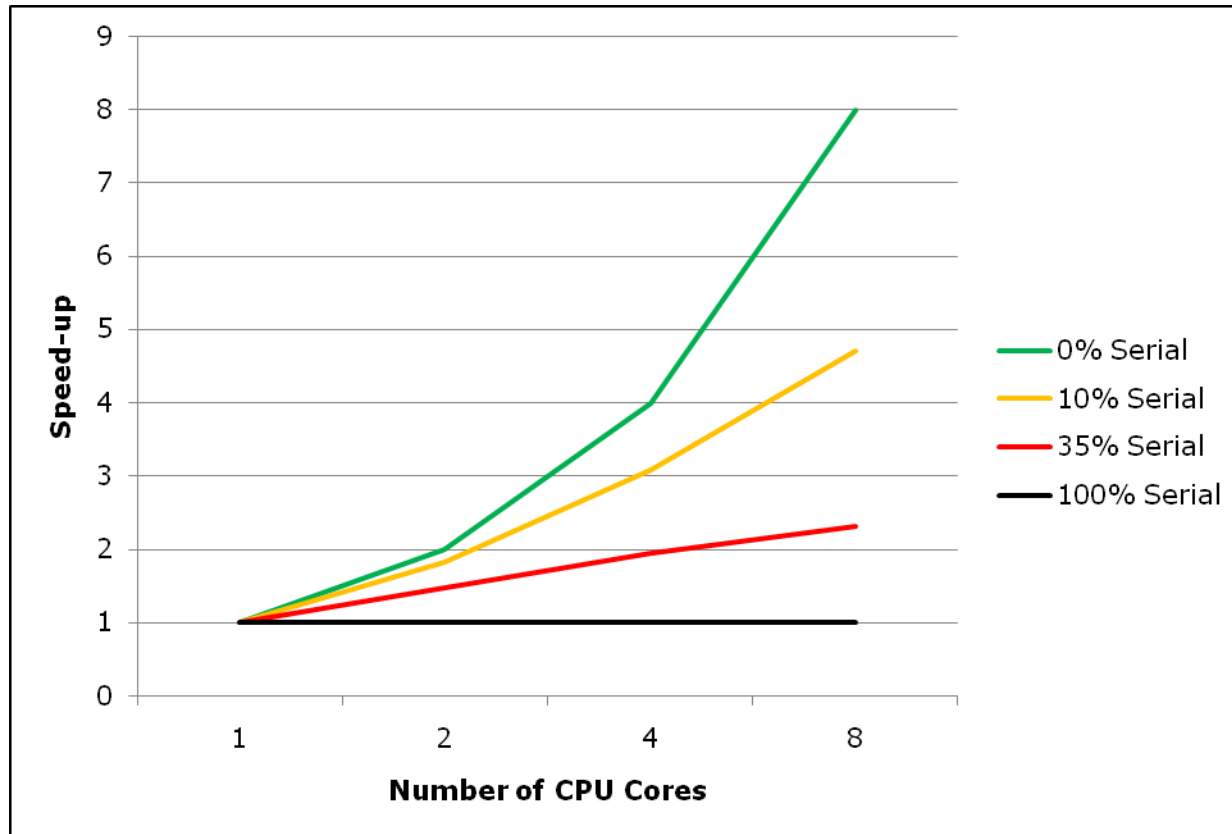


Parallel Programs and Amdahl's Law

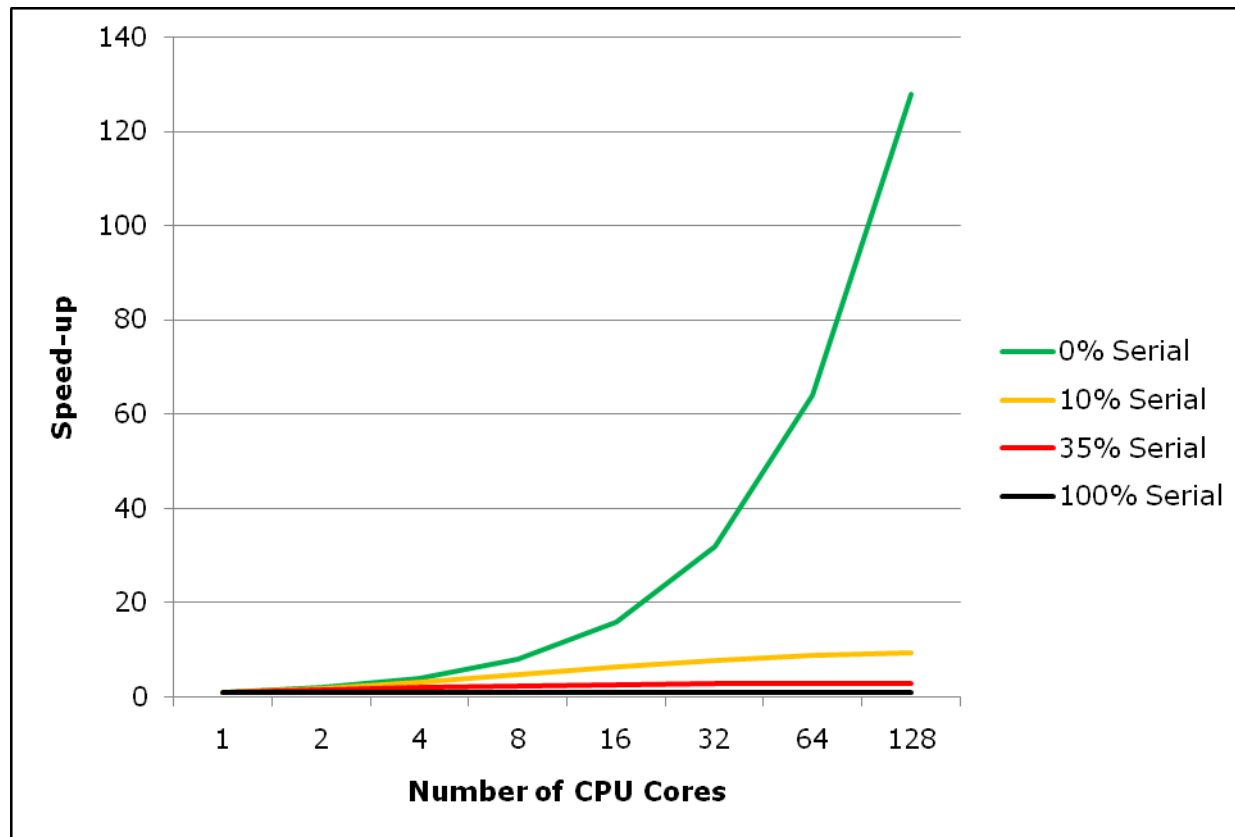
$$\text{Speed-up} = \frac{1}{S_W + (1 - S_W) / N}$$

S_W : % Serial Work

N : Number of processors



Amdahl's Law – Zoom out a bit ...



What about Throughput Computing?

- Measure Performance as *throughput* (vs. *turn-around-time*)
 - How long does it takes to run N “independent” tasks?
 - Multiple cores/threads should be faster than just one
- For basic multi-program throughput, the OS is the “serial component”
 - In some sense, the OS “offloads” work onto available cores
 - As some point, OS scalability becomes the bottleneck
- More advanced applications take on that role themselves
 - Modern databases
 - Some HPC apps turn data parallelism into task-level throughput
 - Future: Managed runtime environments → User mode scheduling
- Can we exploit large scale throughput computing?

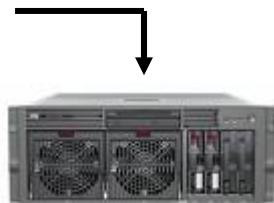


Large Scale Throughput *Systems*

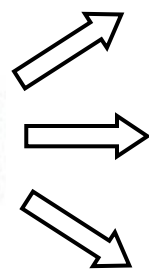
- In these, there are far more threads than HW thread-slots
 - A **Centralized Controller** helps *dispatch/juggle* among threads

Two-Tiered Web Server

Massive amounts of Internet *Clicks*

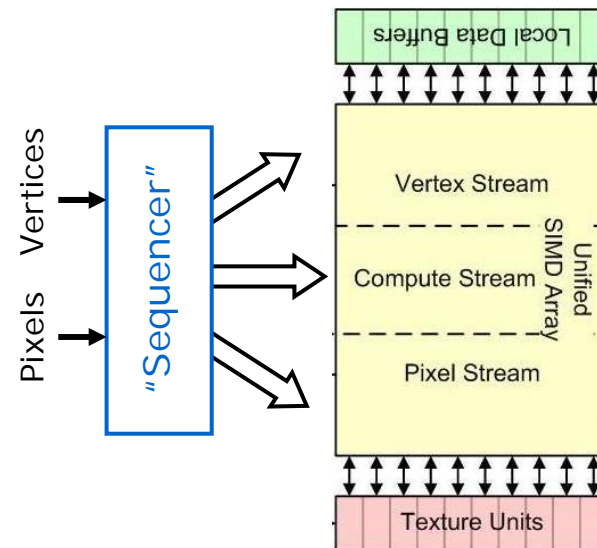


SMP Server:
"Sprayer"



Blade Servers

Modern GPU

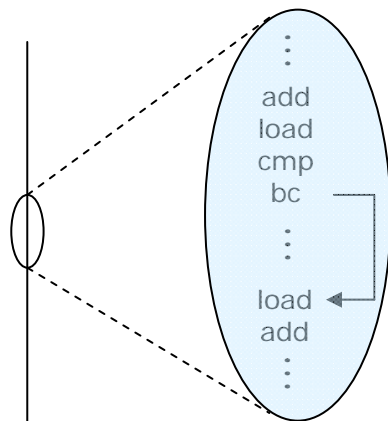


Cooperative *Heterogeneous* Computing!



Data-level Parallelism and Throughput

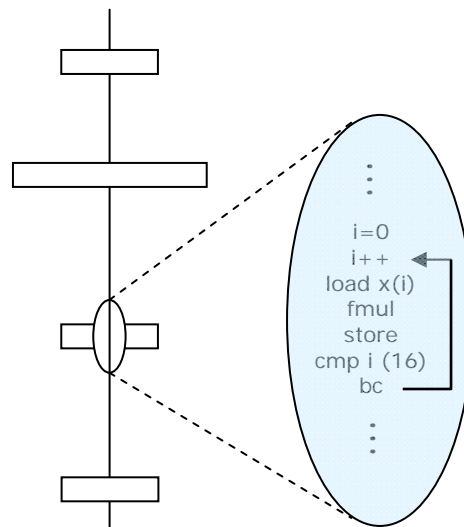
Mostly Serial Code



Typical control flow structure in most code

Some opportunity for instruction-level parallelism

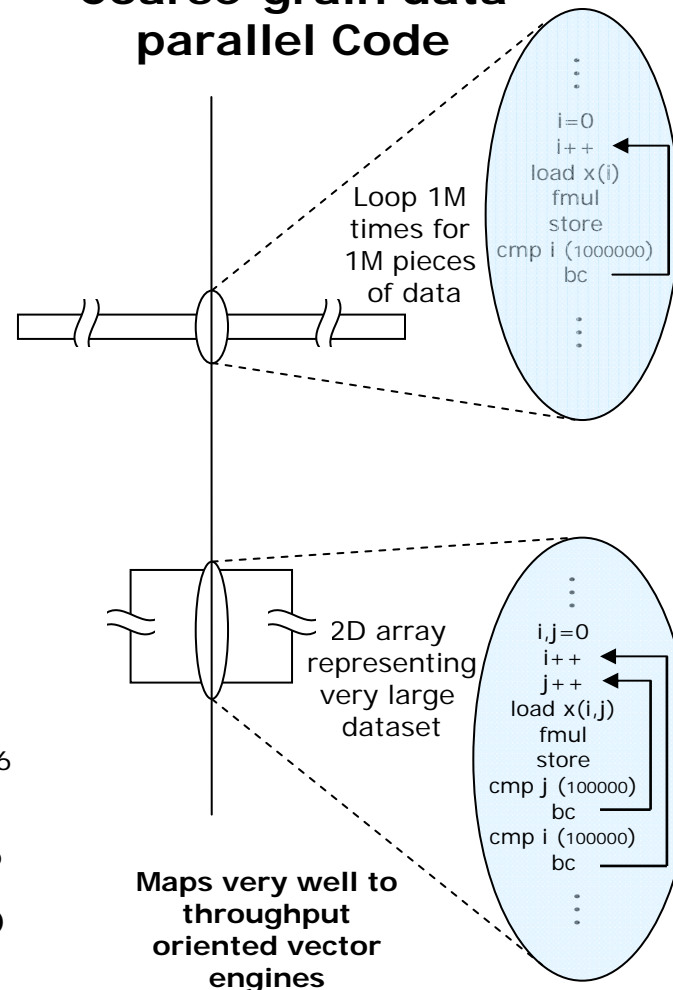
Fine-grain data parallel Code



Loop 16 times for 16 pieces of data

Maps very well to integrated SIMD dataflow (ie: SSE)

Coarse-grain data parallel Code



Loop 1M times for 1M pieces of data

2D array representing very large dataset

Maps very well to throughput oriented vector engines



Components of a Heterogeneous Compute Solution

- Uniprocessor
 - General purpose legacy support
 - Centralized Controller for throughput
- Compute offload engines
 - Small, power-efficient, domain optimized
- Optimized memory system
 - Shared among all processors
 - Optimized communication, synchronization & data transfers
- Simple programming model
 - Favors simplicity and programmer productivity



AMD HPC Strategy

- Deliver industry-leading solutions leveraging:
 - Fine-grain data parallel code support through our CPU roadmaps
 - Maps very well to integrated SIMD dataflow (i.e. SSE)
 - Course-grain data parallel code support through our GPU roadmaps
 - Maps very well to throughput-oriented data parallel engines
- With careful attention to and/or realization of:
 - The increased relevance of data parallel code to adjacent markets and the role of HPC as an enablement springboard
 - The importance of the software development environment
 - The importance of building a balanced system (i.e. memory bandwidth and communication efficiency)
 - Improved reliability of the GPU compute pipelines
 - Performance versus power versus cost trade-offs



Optimized SW for System-level Solutions

- **Long history of Software optimizations for HW “characteristics”**
 - ▶ Optimizing compilers
 - ▶ Cache / TLB blocking
 - ▶ Multi-processor coordination: communication & synchronization
 - ▶ Non-uniform memory characteristics: Process and memory affinity
- **System-level Integration Era will demand even more**
 - ▶ Many Core: user mode and/or managed runtime scheduling?
 - ▶ Heterogeneous Many Core: capability aware scheduling?
- **SW productivity versus optimization dichotomy**
 - ▶ Exposed HW leads to better performance but requires a “platform characteristics aware programming model”
- **Scarcity/Abundance principle favors increased use of Abstractions**
 - ▶ Abstraction leads to Increased productivity but costs performance
 - ▶ Still allow experts burrow down into lower level “on the metal” details



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The Memory Wall – *getting thicker*

There has always been a Critical Balance between
Data Availability and Processing

Situation	When?	Implication	Industry Solutions	
<u>DRAM vs CPU Cycle Time Gap</u>	Early 1990s	Memory wait time dominates computing	Non-blocking caches O-o-O Machines	☺
<u>SW Productivity Crisis: Round 1</u> Object oriented languages; Managed runtime environments	Early 1990s	Larger working sets More diverse data types	Larger Caches Cache Hierarchies Elaborate prefetch	☹
<u>Frequency and IPC Wall</u> CMP and Multi-Threading	2005 and beyond	Multiple working sets! Virtual Machines! More memory accesses	Huge Caches T'put Architectures Elaborate MemCtrls	☹!
<u>SW Productivity Crisis: Round 2</u> Increased abstraction layers Image/Video as basic data types	2009 and beyond	Even larger working sets Larger data types	Stream Computing <i>Chip Stacking?</i>	TBD



The Power Wall

- Easy prediction: *Power will continue to be the #1 design constraint in the System-level Integration Era*
- Why? Several conditions have worsened:
 - V_{\min} will not continue tracking Moore's Law
 - Thermal Design Points (TDPs) in all markets continue to drop
 - Lightly loaded and idle power characteristics are increasingly important in key markets
 - Integration of system-level components also consume chip power
 - A well utilized 100GB/sec DDR memory interface consumes ~15W for the I/O alone!
 - Percent of total U.S. energy consumed by computing devices continues to grow year-on-year



The Power Wall

- Another easy prediction: *Escalating multi-core designs will crash into the power wall just like single cores did due to escalating frequency*
- Why?
 - In order to maintain a reasonable balance, core additions must be accompanied by increases in other resources that consume power (on-chip network, caches, memory and I/O BW, ...)
 - Spiral upwards effect on power
 - The use of multiple cores forces each core to actually slow down
 - At some point, the power limits will not even **allow** you to activate all of the cores at the same time
 - Small, low-power cores tend to be very weak on general purpose workloads
 - The transition to compelling general purpose parallel workloads will not be a fast one
 - Customer value proposition will demand excellent performance on general purpose workloads



The Power Wall -- Implications

- Chip Multiprocessors (CMPs) will evolve to be heterogeneous
 - First, integration of cores with different capabilities
 - Second, integration of alternative programmable devices with superior performance/watt characteristics when running workloads of interest
 - Third, integration of extremely power efficient dedicated hardware assists for very commonly used functions
- Most meaningful metrics are (or will be) a ratio with power
 - Processor Cores and Chips: **Perf/Watt** and **Perf/Watt/\$\$**
 - GPUs & other data parallel throughput solutions: **FLOPS/Watt**
 - I/O SERDES PHYs: **mW/Gbit/sec**
- Very sophisticated next generation power management
 - Fully embrace power as a critical platform-level resource
 - Provision power based on real time monitoring and/or explicit requests
 - SOC components all on separable voltage and clock domains
 - Programmable uController for the base power management controller



Summary – *The System Level Integration Era*

- Chip Multiprocessors are just a first step in this bigger picture
 - Expect to see increased levels of system integration, heterogeneous cores and dedicated accelerators
- Large opportunity space for Microarchitecture innovation
 - Identification of the appropriate components to integrate
 - Establishing system-level balance between compute and integrated functions
 - Improvements in on-chip communication and synchronization
 - Scalable chip-level infrastructure
- Imperatives for the System-level Integration Era
 - Modularity and re-use
 - Never forget the uniprocessor! Continue improving each core.
 - The role of SW and abstractions for completing the picture



Thank You – Have a Great Conference!

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